



INTERNATIONAL
ACCREDITATION
SERVICE®

CERTIFICATE OF ACCREDITATION

This is to attest that

ISE LABS, INC.

46800 BAYSIDE PARKWAY
FREMONT, CALIFORNIA 94538, U.S.A.

Testing Laboratory TL-518

has met the requirements of AC89, *IAS Accreditation Criteria for Testing Laboratories*, and has demonstrated compliance with ISO/IEC Standard 17025:2017, *General requirements for the competence of testing and calibration laboratories*. This organization is accredited to provide the services specified in the scope of accreditation.

Effective Date September 4, 2024



International Accreditation Service
Issued under the authority of IAS management

Visit www.iasonline.org for current accreditation information.

SCOPE OF ACCREDITATION

International Accreditation Service, Inc.

3060 Saturn Street, Suite 100, Brea, California 92821, U.S.A. | www.iasonline.org

ISE LABS, INC.

www.iselabs.com

Location	Address	Contact Name	Contact Phone	Scope pages
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Accredited to ISO/IEC 17025:2017

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Electrical/Environmental	
AEC - Q100	Failure Mechanism Based Stress Test Qualification for Integrated Circuits – (Including Package Drop Test)
AEC - Q100-002	Human Body Model Electrostatic Discharge Test
AEC - Q100-004	Latch Up Test
AEC - Q100-008	Early Life Failure Rate (ELFR)
AEC - Q100-010	Solder Ball Shear Test
AEC - Q100 (Appendix 3)	Plastic Package Opening For Wire Bond Testing (Decapsulation)
AEC – Q101	Failure Mechanism Based Stress Test Qualification for Discrete Semiconductors in Automotive Applications
AEC – Q101-001	Human Body Model (HBM) Electrostatic Discharge (ESD) Test
AEC – Q101-003	Wire Bond Shear Test
AEC – Q101-005	Capacity Discharge Model (CDM) Electrostatic Discharge (ESD)
ANSI/ESDA/JEDEC JS-002	Charged Device Model (CDM) – Device Level
EIA-IPC-JEDEC J-STD-002	Solderability
GR-326-CORE	General Req for Single Mode Optical Connectors and Jumper Assemblies
GR-468-CORE	Generic REL Assurance Req for Optoelectronic Devices in Telecom Equipment



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GR-1209-CORE	General Req for Passive Optical Components
J-STD-020	Moisture - Reflow Sensitivity Classification For Non-Hermetic Solid State Surface Devices
JESD22 A101	Steady State Temperature Humidity Bias Life Test
JESD22 A102	Accelerated Moisture Resistance Unbiased Autoclave
JESD22 A103	High Temperature Storage Life
JESD22 A104	Temperature Cycling
JESD22 A105	Power And Temperature Cycling
JESD22 A108	Temperature, Bias, And Operating Life
JESD22 A110	Highly Accelerated Temperature And Humidity Stress Test Hast
JESD22 A113	Preconditioning Of Non-Hermetic Surface Mount Devices Prior To Reliability Testing
JESD22 A118	Accelerated Moisture Resistance Unbiased Hast
JESD22 B100	Physical Dimensions
JESD22 B103	Vibration Variable Frequency
JESD22 B105	Lead Integrity
MIL-STD-883	Seal /Gross & Fine Leak (Method 1014)
MIL-STD-883	Constant Acceleration (Method 2001)
MIL-STD-883	Bond Strength (Destructive Bond Pull Test) (Method 2011)
MIL-STD-883	(Method 2019) Die Shear Strength
MIL-STD-883	Ultrasonic Inspection of Die Attached (CSAM) (Method 2030.1)
TIA-455-129	Procedure for Applying Human Body Model Electrostatic Discharge Stress to Package Optoelectronic Components

